

## 3A, Low Voltage Low Dropout Regulator

### Features

- 3.0A Minimum Guaranteed Output Current
- 550 mV Maximum Dropout Voltage over Temperature
- Ideal for 3.0V to 2.5V Conversion
- Ideal for 2.5V to 1.8V Conversion
- 1% Initial Accuracy
- Low Ground Current
- Current Limiting and Thermal Shutdown
- Reversed-Battery Protection
- Reversed-Leakage Protection
- Fast Transient Response
- TO-263 (D<sup>2</sup>Pak) and TO-220 Packaging
- TTL/CMOS Compatible Enable Pin (MIC39301/2 Only)
- Error Flag Output (MIC39301 Only)
- Adjustable Output (MIC39302 Only)

### Applications

- LDO Linear Regulator for PC Add-In Cards
- High-Efficiency Linear Power Supplies
- SMPS Post Regulator
- Multimedia and PC Processor Supplies
- Low Voltage Microcontrollers
- StrongARM Processor Supply

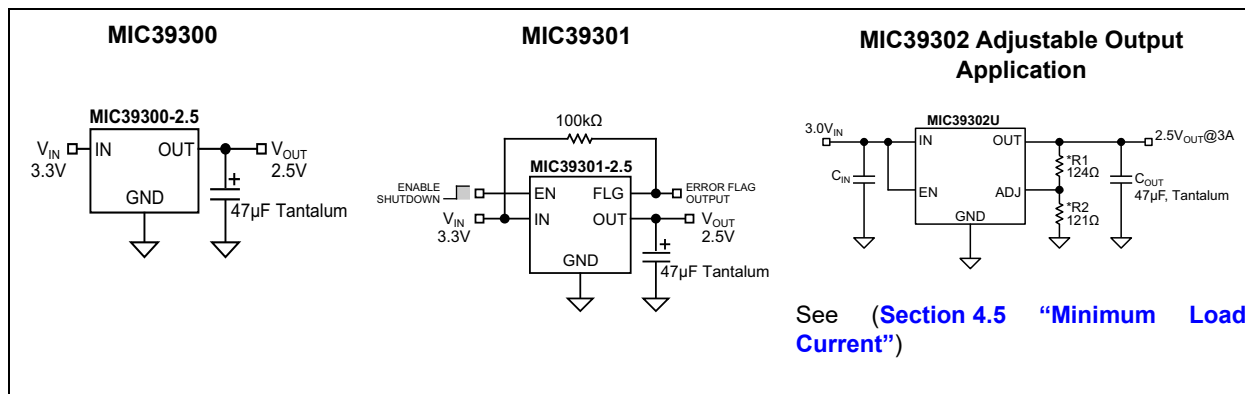
### General Description

The MIC39300, MIC39301, and MIC39302 are 3.0A low-dropout linear voltage regulators that provide a low voltage, high-current output with a minimum of external components. Utilizing Microchip's proprietary Super  $\beta$  PNP pass element, the MIC39300/1/2 offers extremely low dropout (typically 385 mV at 3.0A) and low ground current (typically 36 mA at 3.0A).

The MIC39300/1/2 are ideal for PC add-in cards that need to convert from standard 3.3V to 2.5V or 2.5V to 1.8V. A guaranteed maximum dropout voltage of 500 mV over all operating conditions allows the MIC39300/1/2 to provide 2.5V from a supply as low as 3V, and 1.8V from a supply as low as 2.5V. The MIC39300/1/2 also have fast transient response for heavy switching applications. The device requires only 47  $\mu$ F of output capacitance to maintain stability and achieve fast transient response.

The MIC39300/1/2 are fully protected with overcurrent limiting, thermal shutdown, reversed-battery protection, reversed-leakage protection, and reversed-lead insertion. The MIC39301 offers a TTL-logic compatible enable pin and an error flag that indicates undervoltage and overcurrent conditions. Offered in fixed voltages, the MIC39300/1 come in the TO-220 and TO-263 (D<sup>2</sup>Pak) packages and are an ideal upgrade to older, NPN-based linear voltage regulators. The MIC39302 adjustable option allows programming the output voltage anywhere between 1.24V and 15.5V and is offered in a 5-Pin TO-263 (D<sup>2</sup>Pak) package.

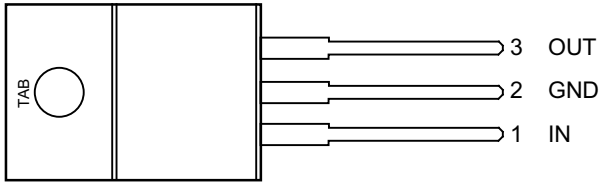
### Typical Application Circuits



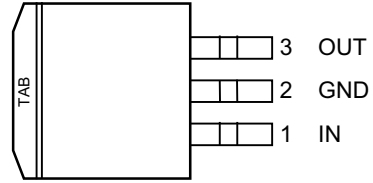
# MIC39300/01/02

## Package Types

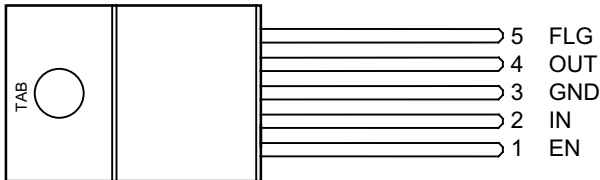
**MIC39300-x.xBT**  
TO-220-3 (T)



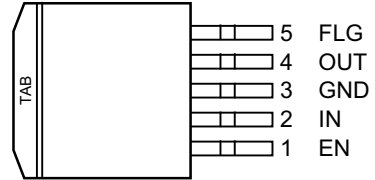
**MIC39300-x.xBU**  
TO-263-3 (U)



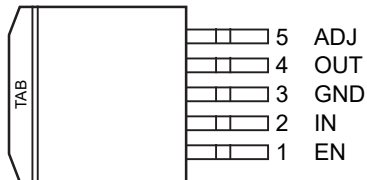
**MIC39301-x.xBT**  
TO-220-5 (T)



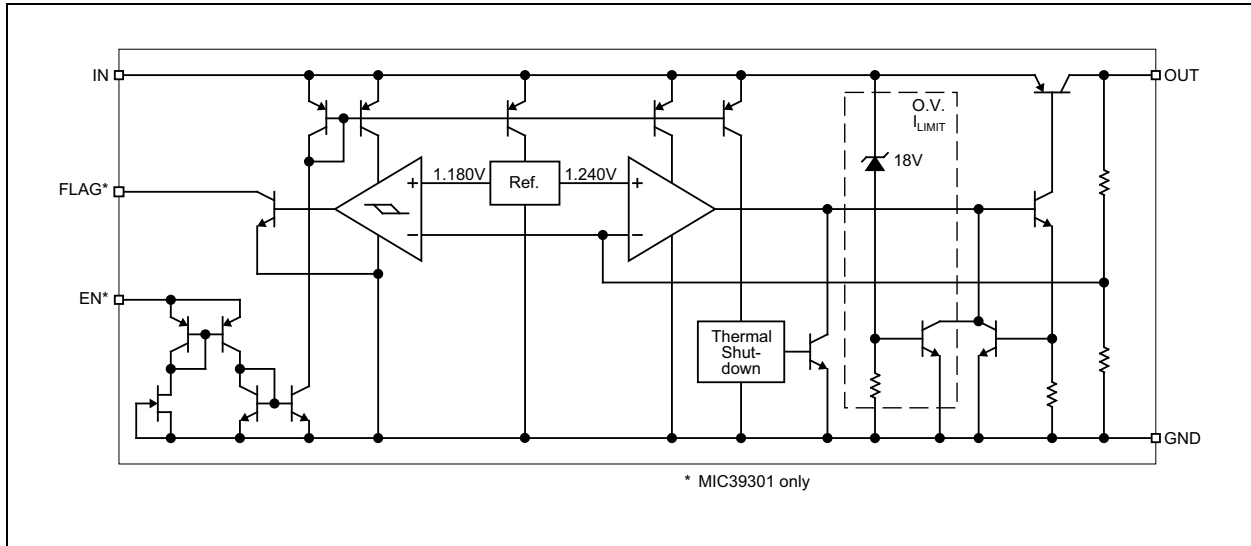
**MIC39301-x.xBU**  
TO-263-5 (D<sup>2</sup>Pak) (U)



**MIC39302WU**  
TO-263-5 (D<sup>2</sup>Pak) (U)



## Functional Block Diagram



# MIC39300/01/02

## 1.0 ELECTRICAL CHARACTERISTICS

### Absolute Maximum Ratings †

Supply Voltage ( $V_{IN}$ ).....	-20V to +20V
Enable Voltage ( $V_{EN}$ ).....	+20V
ESD Rating (Note 1).....	ESD Sensitive

### Operating Ratings ‡

Supply Voltage ( $V_{IN}$ ).....	+2.5V to +16V
Enable Voltage ( $V_{EN}$ ).....	+16V
Maximum Power Dissipation ( $P_{D(max)}$ ).....	(Note 2)

† **Notice:** Stresses above those listed under “Absolute Maximum Ratings” may cause permanent damage to the device. This is a stress rating only and functional operation of the device at those or any other conditions above those indicated in the operational sections of this specification is not intended. Exposure to maximum rating conditions for extended periods may affect device reliability. Specifications are for packaged product only.

‡ **Notice:** The device is not guaranteed to function outside its operating ratings.

**Note 1:** Devices are ESD sensitive. Handling precautions are recommended.

**2:**  $P_{D(max)} = (T_{J(max)} - T_A) \div \theta_{JA}$ , where  $\theta_{JA}$  depends upon the printed circuit layout. See [Section 4.0 “Application Information”](#) section.

**TABLE 1-1: ELECTRICAL CHARACTERISTICS**

**Electrical Characteristics:**  $T_J = 25^\circ\text{C}$ , **Bold** values indicate  $-40^\circ\text{C} \leq T_J \leq +125^\circ\text{C}$ ; unless otherwise specified.

Parameter	Symbol	Min.	Typ.	Max.	Units	Conditions
Output Voltage	$V_{OUT}$	-1	—	1	%	10 mA
		<b>-2</b>		<b>2</b>	%	$10 \text{ mA} \leq I_{OUT} \leq 3\text{A}, V_{OUT} + 1\text{V} \leq V_{IN} \leq 8\text{V}$
Line Regulation	$\Delta V_{OUT}/\Delta V_{IN}$	—	0.06	0.5	%	$I_{OUT} = 10 \text{ mA}, V_{OUT} + 1\text{V} \leq V_{IN} \leq 8\text{V}$
Load Regulation	$\Delta V_{OUT}/V_{OUT}$	—	0.2	1	%	$V_{IN} = V_{OUT} + 1\text{V}, 10 \text{ mA} \leq I_{OUT} \leq 3\text{A}$
Output Voltage Temperature Coefficient (Note 1)	$\Delta V_{OUT}/\Delta T$	—	<b>20</b>	<b>100</b>	ppm/°C	—
Dropout Voltage (Note 2), (Note 4)	$V_{DO}$	—	65	<b>200</b>	mV	$I_{OUT} = 100 \text{ mA}, \Delta V_{OUT} = -1\%$
		—	185	—	mV	$I_{OUT} = 750 \text{ mA}, \Delta V_{OUT} = -1\%$
		—	250	—	mV	$I_{OUT} = 1.5\text{A}, \Delta V_{OUT} = -1\%$
		—	385	<b>550</b>	mV	$I_{OUT} = 3\text{A}, \Delta V_{OUT} = -1\%$
Ground Current (Note 3)	$I_{GND}$	—	10	<b>20</b>	mA	$I_{OUT} = 750 \text{ mA}, V_{IN} = V_{OUT} + 1\text{V}$
		—	17	—	mA	$I_{OUT} = 1.5\text{A}, V_{IN} = V_{OUT} + 1\text{V}$
		—	45	—	mA	$I_{OUT} = 3\text{A}, V_{IN} = V_{OUT} + 1\text{V}$
Dropout Ground Pin Current	$I_{GND(do)}$	—	6	—	mA	$V_{IN} \leq V_{OUT}(\text{nominal}) - 0.5\text{V}, I_{OUT} = 10 \text{ mA}$
Current Limit	$I_{OUT(lim)}$	—	4.5	—	A	$V_{OUT} = 0\text{V}, V_{IN} = V_{OUT} + 1\text{V}$
<b>Enable Input (MIC39301)</b>						
Enable Input Voltage	$V_{EN}$	—	—	<b>0.8</b>	V	Logic low (OFF)
		<b>2.5</b>	—	—	V	Logic high (ON)

**Electrical Characteristics:**  $T_J = 25^\circ\text{C}$ , **Bold** values indicate  $-40^\circ\text{C} \leq T_J \leq +125^\circ\text{C}$ ; unless otherwise specified.

Parameter	Symbol	Min.	Typ.	Max.	Units	Conditions
Enable Input Current	$I_{IN}$	1	15	<b>30</b>	$\mu\text{A}$	$V_{EN} = 2.5\text{V}$
		—	—	<b>75</b>	$\mu\text{A}$	
		—	—	2	$\mu\text{A}$	$V_{EN} = 0.8\text{V}$
		—	—	<b>4</b>	$\mu\text{A}$	
Shutdown Output Current (Note 5)	$I_{OUT(shdn)}$	—	10	<b>20</b>	$\mu\text{A}$	—
<b>Flag Output (MIC39301)</b>						
Output Leakage Current	$I_{FLG(leak)}$	—	0.01	<b>1</b>	$\mu\text{A}$	$V_{IN} = 16\text{V}$
		—	—	<b>2</b>		
Output Low Voltage (Note 4)	$V_{FLG(do)}$	—	220	300	mV	$V_{IN} = 2.50\text{V}$ , $I_{OL} = 250 \mu\text{A}$
		—	—	<b>400</b>		
Low Threshold	$V_{FLG}$	93	—	—	%	% of $V_{OUT}$
High Threshold		—	—	99.2	%	% of $V_{OUT}$
Hysteresis		—	1	—	%	—
<b>Reference (Adjust Pin) - MIC39302 Only</b>						
Reference Voltage	$V_{ADJ}$	1.228	1.240	1.252	V	—
		<b>1.215</b>	—	<b>1.265</b>		
Reference Voltage Temp. Coefficient (Note 6)	$V_{TC}$	—	20	—	ppm/ $^\circ\text{C}$	—
Adjust Pin Bias Current	$I_{ADJ}$	—	40	80	nA	—
		—	—	<b>120</b>		
Adjust Pin Bias Current Temp. Coefficient	$I_{TC}$	—	0.1	—	nA/ $^\circ\text{C}$	—

- 1: Output voltage temperature coefficient is  $\Delta V_{OUT}(\text{worst case}) \div (T_{J(\text{max})} - T_{J(\text{min})})$  where  $T_{J(\text{max})}$  is  $+125^\circ\text{C}$  and  $T_{J(\text{min})}$  is  $-40^\circ\text{C}$ .
- 2:  $V_{DO} = V_{IN} - V_{OUT}$  when  $V_{OUT}$  decreases to 99% of its nominal output voltage with  $V_{IN} = V_{OUT} + 1\text{V}$ . For output voltages below 2.5V, dropout voltage is the input-to-output voltage differential with the minimum input voltage being 2.5V. Minimum input operating voltage is 2.5V.
- 3:  $I_{GND}$  is the quiescent current.  $I_{IN} = I_{GND} + I_{OUT}$ .
- 4: For a 1.8V device,  $V_{IN} = 2.5\text{V}$ .
- 5:  $V_{EN} \leq 0.8\text{V}$ ,  $V_{IN} \leq 8\text{V}$ , and  $V_{OUT} = 0\text{V}$ .
- 6: Thermal regulation is defined as the change in output voltage at a time  $t$  after a change in power dissipation is applied, excluding load or line regulation effects. Specifications are for a 200 mA load pulse at  $V_{IN} = 8\text{V}$  for  $t = 10 \text{ms}$ .

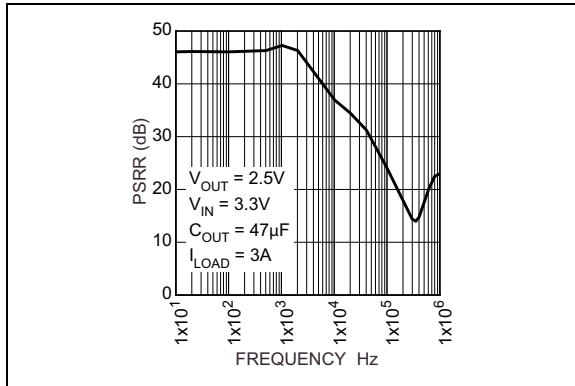
## TEMPERATURE SPECIFICATIONS (Note 1)

Parameters	Sym.	Min.	Typ.	Max.	Units	Conditions
<b>Temperature Ranges</b>						
Lead Temperature	—	—	—	260	°C	Soldering, 5 sec.
Junction Operating Temperature Range	$T_J$	-40	—	+125	°C	—
Storage Temperature Range	$T_S$	-65	—	+150	°C	—
<b>Package Thermal Resistances</b>						
Thermal Resistance TO-263	$\theta_{JC}$	—	2	—	°C/W	—
Thermal Resistance TO-220	$\theta_{JC}$	—	2	—	°C/W	—

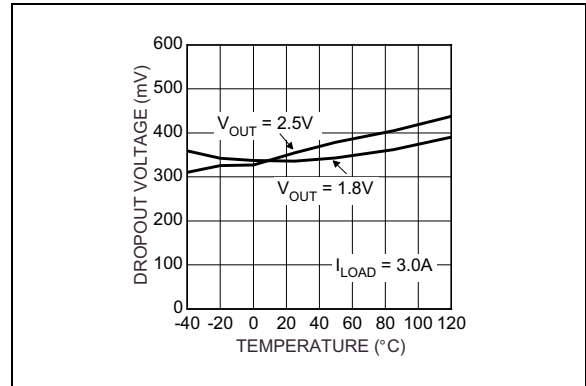
**Note 1:** The maximum allowable power dissipation is a function of ambient temperature, the maximum allowable junction temperature and the thermal resistance from junction to air (i.e.,  $T_A$ ,  $T_J$ ,  $\theta_{JA}$ ). Exceeding the maximum allowable power dissipation will cause the device operating junction temperature to exceed the maximum +125°C rating. Sustained junction temperatures above +125°C can impact the device reliability.

## 2.0 TYPICAL PERFORMANCE CURVES

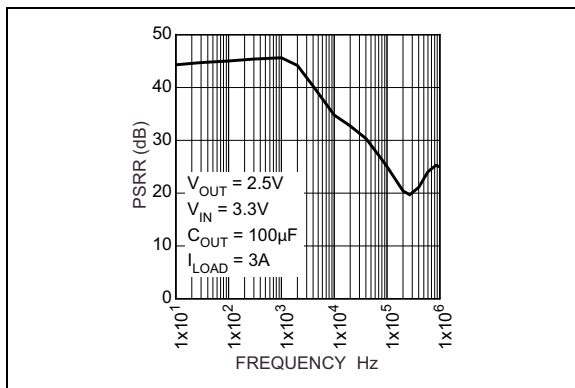
**Note:** The graphs and tables provided following this note are a statistical summary based on a limited number of samples and are provided for informational purposes only. The performance characteristics listed herein are not tested or guaranteed. In some graphs or tables, the data presented may be outside the specified operating range (e.g., outside specified power supply range) and therefore outside the warranted range.



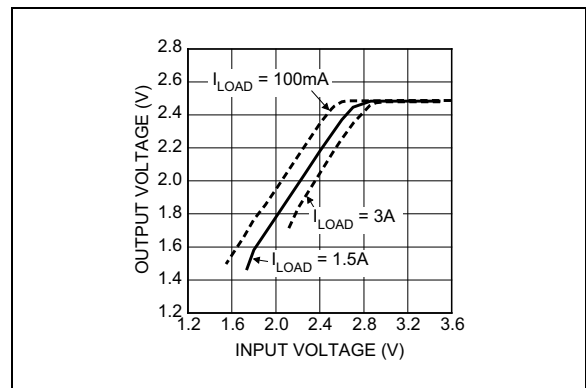
**FIGURE 2-1:** Power Supply vs. Ripple Rejection.



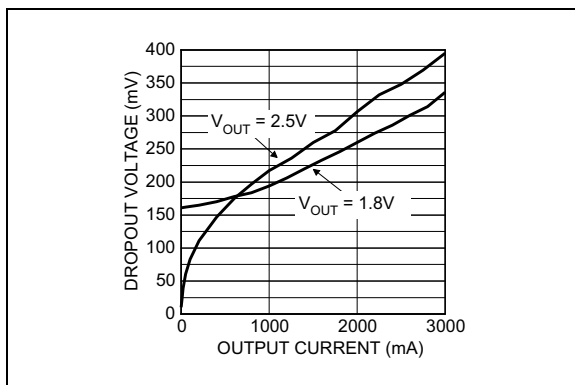
**FIGURE 2-4:** Dropout Voltage vs. Temperature.



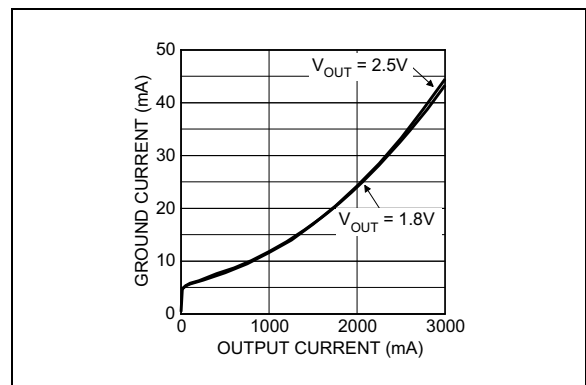
**FIGURE 2-2:** Power Supply vs. Ripple Rejection.



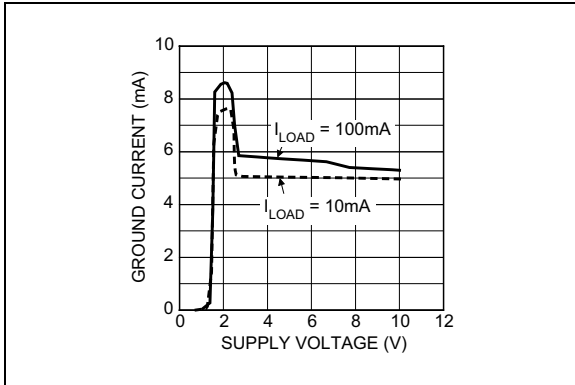
**FIGURE 2-5:** Dropout Characteristics.



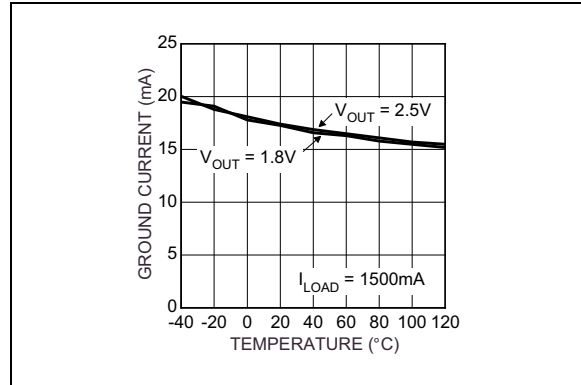
**FIGURE 2-3:** Dropout Voltage vs. Output Current.



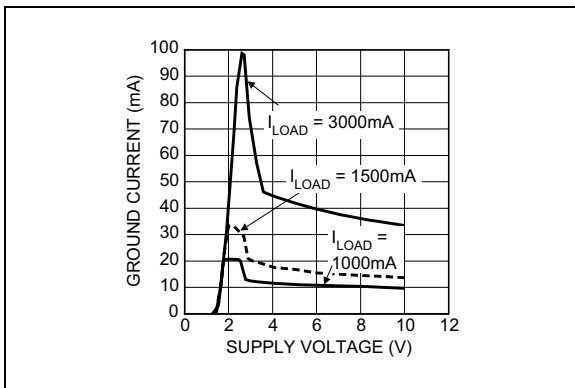
**FIGURE 2-6:** Ground Current vs. Output Current.



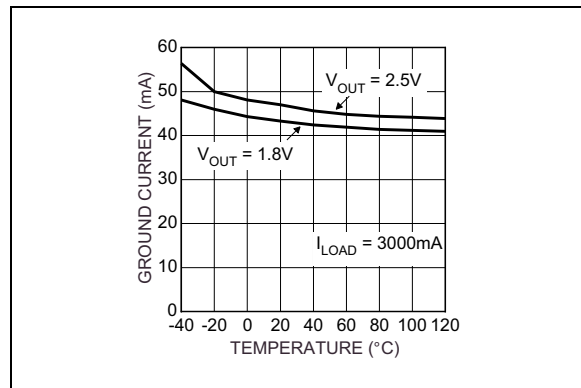
**FIGURE 2-7:** Ground Current vs. Supply Voltage.



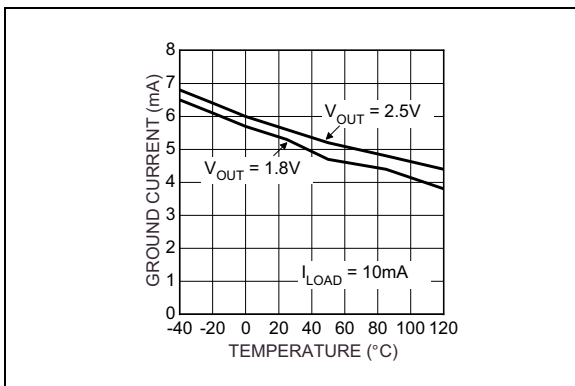
**FIGURE 2-10:** Ground Current vs. Temperature.



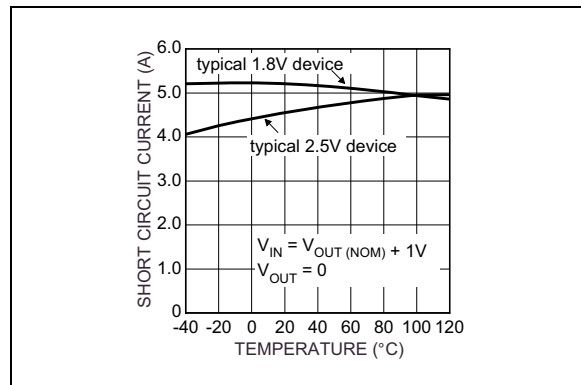
**FIGURE 2-8:** Ground Current vs. Supply Voltage.



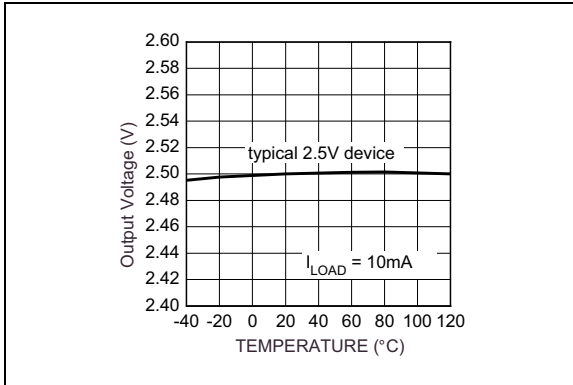
**FIGURE 2-11:** Ground Current vs. Temperature.



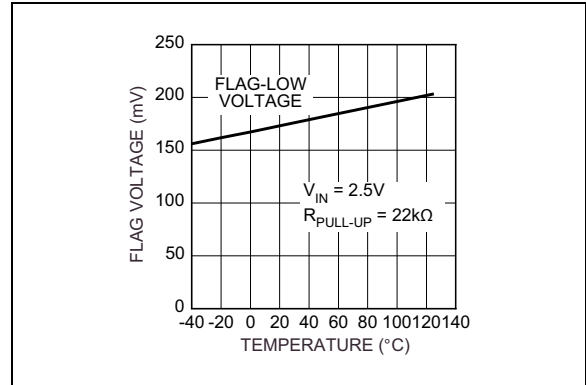
**FIGURE 2-9:** Ground Current vs. Temperature.



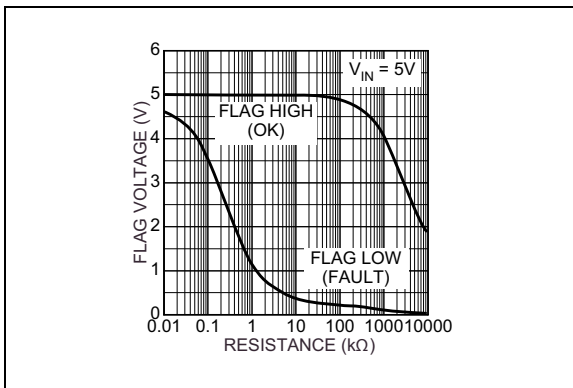
**FIGURE 2-12:** Short Circuit vs. Temperature.



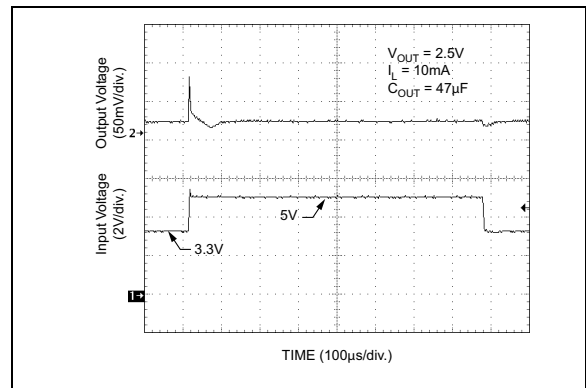
**FIGURE 2-13:** Output Voltage vs. Temperature.



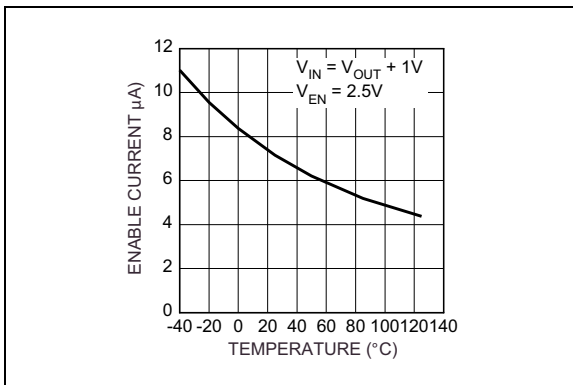
**FIGURE 2-16:** Flag-Low Voltage vs. Temperature.



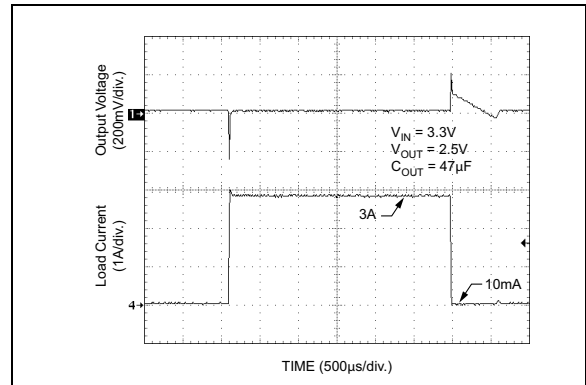
**FIGURE 2-14:** Error Flag Pull-Up Resistor.



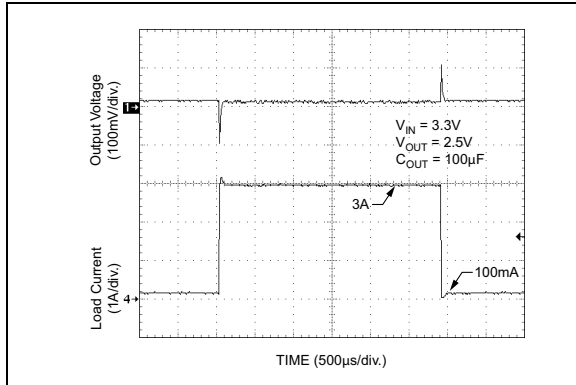
**FIGURE 2-17:** Line Transient Response.



**FIGURE 2-15:** Enable Current vs. Temperature.



**FIGURE 2-18:** Load Transient Response.



**FIGURE 2-19:** Load Transient Response.

## 3.0 PIN DESCRIPTIONS

The descriptions of the pins are listed in [Table 3-1](#).

**TABLE 3-1: PIN FUNCTION TABLE**

Pin Number MIC39300	Pin Number MIC39301	Pin Number MIC39302	Pin Name	Description
—	1	1	EN	Enable (Input): TTL/CMOS compatible input. Logic-high = enable; logic-low or open = shutdown.
1	2	2	IN	Unregulated Input: +16V maximum supply.
2, TAB	3, TAB	3, TAB	GND	Ground: Ground pin and TAB are internally connected.
3	4	4	OUT	Regulator Output.
—	5	—	FLG	Error Flag (Output): Open-collector indicates an output fault condition. Active low.
—	—	5	ADJ	Adjustable Regulator Feedback Input: Connect to the resistor voltage divider that is placed from OUT to GND in order to set the output voltage.

## 4.0 APPLICATION INFORMATION

The MIC39300/1/2 are high-performance, low-dropout voltage regulators suitable for moderate to high-current voltage regulator applications. Its 550 mV dropout voltage at full load makes it especially valuable in battery-powered systems and as a high-efficiency noise filter in post-regulator applications. Unlike older NPN-pass transistor designs, where the minimum dropout voltage is limited by the base-to-emitter voltage drop and collector-to-emitter saturation voltage, dropout performance of the PNP output of these devices is limited only by the low  $V_{CE}$  saturation voltage.

A trade-off for the low dropout voltage is a varying base drive requirement. Microchip's Super  $\beta$  PNP process reduces this drive requirement to only 2% to 5% of the load current.

The MIC39300/1/2 regulators are fully protected from damage due to fault conditions. Current limiting is provided. This limiting is linear; output current during overload conditions is constant. Thermal shutdown disables the device when the die temperature exceeds the maximum safe operating temperature. Transient protection allows device (and load) survival even when the input voltage spikes above and below nominal. The output structure of these regulators allows voltages in excess of the desired output voltage to be applied without reverse current flow.

### 4.1 Thermal Design

Linear regulators are simple to use. The most complicated design parameters to consider are thermal characteristics. Thermal design requires four application-specific parameters:

- Maximum ambient temperature ( $T_A$ )
- Output Current ( $I_{OUT}$ )
- Output Voltage ( $V_{OUT}$ )
- Input Voltage ( $V_{IN}$ )
- Ground Current ( $I_{GND}$ )

Calculate the power dissipation of the regulator from these numbers and the device parameters from this datasheet, where the ground current is taken from the data sheet.

#### EQUATION 4-1:

$$P_D = (V_{IN} - V_{OUT})I_{OUT} + V_{IN} \times I_{GND}$$

The heat sink thermal resistance is determined by:

#### EQUATION 4-2:

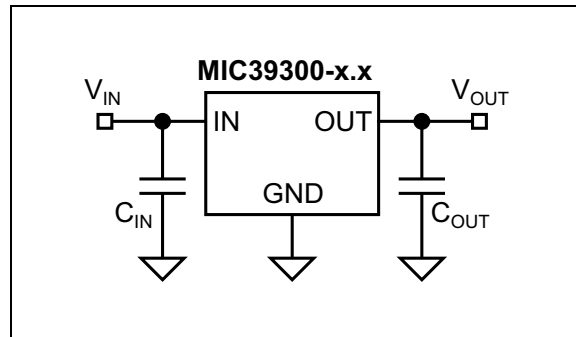
$$\theta_{SA} = \frac{T_{J(MAX)} - T_A}{P_D} - (\theta_{JC} + \theta_{CS})$$

Where:

$$\begin{aligned} T_{J(MAX)} &\leq 125^\circ\text{C} \\ \theta_{CS} &\text{Between } 0^\circ\text{C/W and } 2^\circ\text{C/W} \end{aligned}$$

The heat sink may be significantly reduced in applications where the minimum input voltage is known and is large compared with the dropout voltage. Use a series input resistor to drop excessive voltage and distribute the heat between this resistor and the regulator. The low dropout properties of Microchip's Super  $\beta$  PNP regulators allow significant reductions in regulator power dissipation and the associated heat sink without compromising performance. When this technique is employed, a capacitor of at least 1.0  $\mu\text{F}$  is needed directly between the input and regulator ground.

Refer to [Application Note 9](#) for further details and examples on thermal design and heat sink specification.



**FIGURE 4-1:** Capacitor Requirements.

### 4.2 Output Capacitor

The MIC39300/1/2 requires an output capacitor to maintain stability and improve transient response. Proper capacitor selection is important to ensure proper operation. The MIC39300/1/2 output capacitor selection is dependent upon the ESR (equivalent series resistance) of the output capacitor to maintain stability. When the output capacitor is 47  $\mu\text{F}$  or greater, the output capacitor should have less than 1 $\Omega$  of ESR. This will improve transient response as well as promote stability. Ultra low ESR capacitors, such as ceramic chip capacitors may promote instability. These very low ESR levels may cause an oscillation and/or underdamped transient response. A low-ESR solid tantalum capacitor works extremely well and provides

good transient response and stability over temperature. Aluminum electrolytics can also be used, as long as the ESR of the capacitor is  $< 1\Omega$ .

The value of the output capacitor can be increased without limit. Higher capacitance values help to improve transient response and ripple rejection and reduce output noise.

### 4.3 Input Capacitor

An input capacitor of  $1\mu\text{F}$  or greater is recommended when the device is more than 4 inches away from the bulk AC supply capacitance or when the supply is a battery. Small, surface mount, ceramic chip capacitors can be used for bypassing. Larger values will help to improve ripple rejection by bypassing the input to the regulator, further improving the integrity of the output voltage.

### 4.4 Transient Response and 3.3V to 2.5V and 2.5V to 1.8V Conversions

The MIC39300/1/2 has excellent transient response to variations in input voltage and load current. The device has been designed to respond quickly to load current variations and input voltage variations. Large output capacitors are not required to obtain this performance. A standard  $47\mu\text{F}$  output capacitor, preferably tantalum, is all that is required. Larger values help to improve performance even further.

By virtue of its low dropout voltage, this device does not saturate into dropout as readily as similar NPN-based designs. When converting from 3.3V to 2.5V or 2.5V to 1.8V, the NPN-based regulators are already operating in dropout, with typical dropout requirements of 1.2V or greater. To convert down to 2.5V without operating in dropout, NPN-based regulators require an input voltage of 3.7V at the very least. The MIC39300/1 regulator will provide excellent performance with an input as low as 3.0V or 2.5V. This gives the PNP-based regulators a distinct advantage over older, NPN-based linear regulators.

### 4.5 Minimum Load Current

The MIC39300/1/2 regulators are specified between finite loads. If the output current is too small, leakage currents dominate and the output voltage rises. A 10 mA minimum load current is necessary for proper regulation.

### 4.6 Error Flag

The MIC39301 version features an error flag circuit that monitors the output voltage and signals an error condition when the voltage drops 5% below the nominal output voltage. The error flag is an open-collector output that can sink 10 mA during a fault condition.

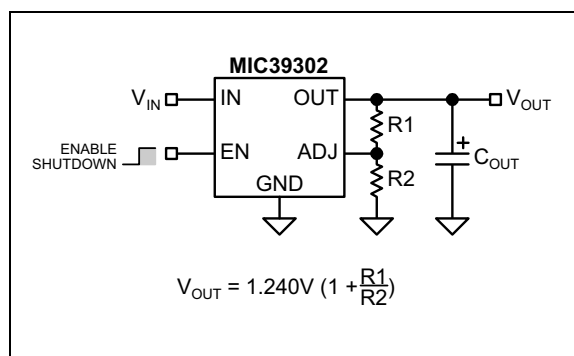
Low output voltage can be caused by a number of problems, including an overcurrent fault (device in current limit) or low input voltage. The flag is inoperative during overtemperature shutdown.

When the error flag is not used, it is best to leave it open. A pull-up resistor from FLG to either  $V_{\text{IN}}$  or  $V_{\text{OUT}}$  is required for proper operation.

### 4.7 Enable Input

The MIC39301/2 feature an enable input for on/off control of the device. The enable input's shutdown state draws "zero" current (only microamperes of leakage). The enable input is TTL/CMOS compatible for simple logic interface, but can be connected to up to 20V. When enabled, it draws approximately  $15\mu\text{A}$ .

### 4.8 Adjustable Regulator Design



**FIGURE 4-2:** Adjustable Regulator with Resistors.

The MIC39302 allows programming the output voltage anywhere between 1.24V and 15.5V. Two resistors are used. The resistor values are calculated by:

#### EQUATION 4-3:

$$R1 = R2 \left( \frac{V_{\text{OUT}}}{1.240} - 1 \right)$$

Where  $V_{\text{OUT}}$  is the desired output voltage. Figure 4-2 shows the component definition. Applications with widely varying load currents may scale the resistors to draw the minimum load current required for proper operation (see Section 4.5 "Minimum Load Current").

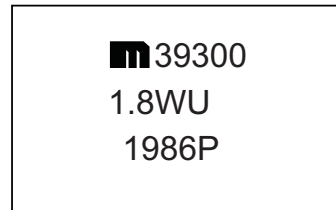
## 5.0 PACKAGING INFORMATION

### 5.1 Package Marking Information

3-Lead TO-263\*



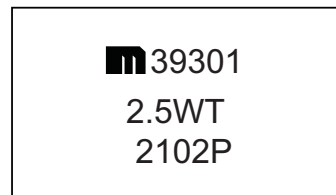
Example



5-Lead TO-220\*



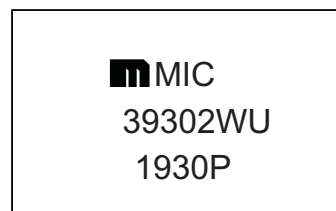
Example



D<sup>2</sup>PAK\*



Example



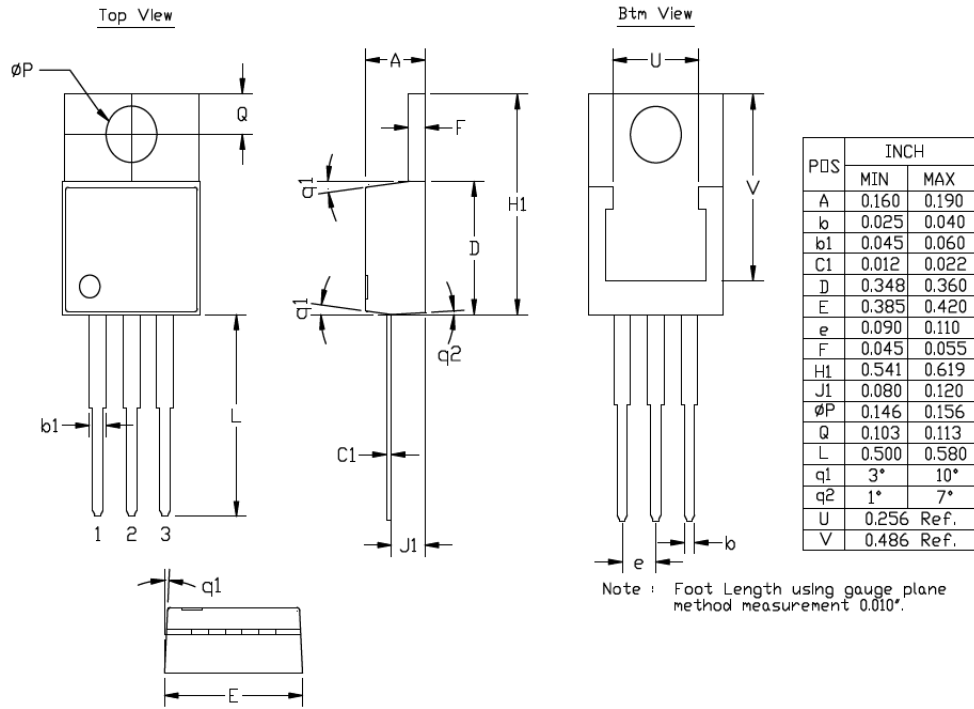
<b>Legend:</b>	XX...X	Product code or customer-specific information
	Y	Year code (last digit of calendar year)
	YY	Year code (last 2 digits of calendar year)
	WW	Week code (week of January 1 is week '01')
	NNN	Alphanumeric traceability code
	(e3)	Pb-free JEDEC <sup>®</sup> designator for Matte Tin (Sn)
	*	This package is Pb-free. The Pb-free JEDEC designator (e3) can be found on the outer packaging for this package.
	•, ▲, ▼	Pin one index is identified by a dot, delta up, or delta down (triangle mark).
<b>Note:</b>	In the event the full Microchip part number cannot be marked on one line, it will be carried over to the next line, thus limiting the number of available characters for customer-specific information. Package may or may not include the corporate logo.	
	Underbar (¯) and/or Overbar (˘) symbol may not be to scale.	

## 3-Lead TO-220 Package Outline and Recommended Land Pattern

**TITLE**

3 LEAD TO220 PACKAGE OUTLINE & RECOMMENDED LAND PATTERN

<b>DRAWING #</b>	TO220-3LD-PL-1	<b>UNIT</b>	INCH
<b>Lead Frame</b>	Copper Alloy	<b>Lead Finish</b>	Matte Tin



Note: For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>.

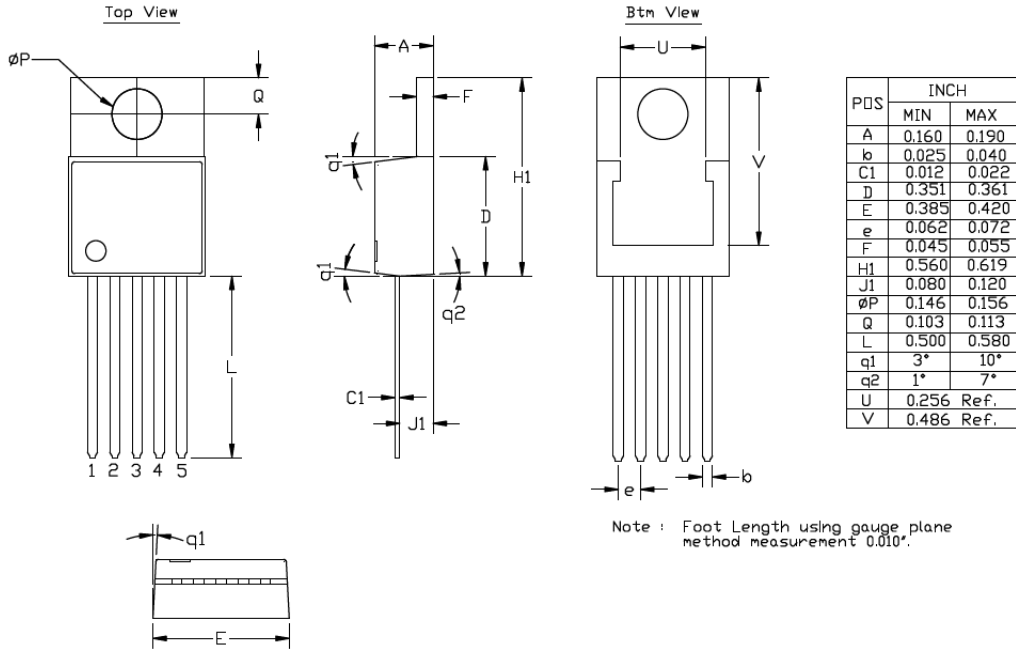
# MIC39300/01/02

## 5-Lead TO-220 Package Outline and Recommended Land Pattern

**TITLE**

5 LEAD TO220 PACKAGE OUTLINE & RECOMMENDED LAND PATTERN

<b>DRAWING #</b>	TO220-5LD-PL-1	<b>UNIT</b>	INCH
<b>Lead Frame</b>	Copper Alloy	<b>Lead Finish</b>	Matte Tin



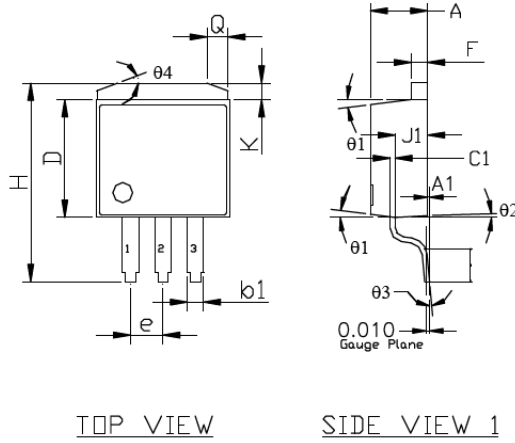
Note: For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>.

## 3-Lead TO-263 Package Outline and Recommended Land Pattern

**TITLE**

3 LEAD TO263 PACKAGE OUTLINE & RECOMMENDED LAND PATTERN

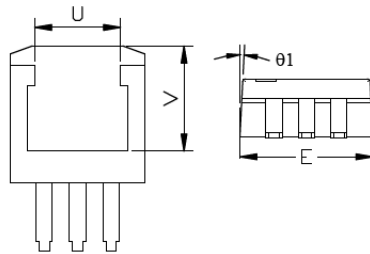
<b>DRAWING #</b>	TO263-3LD-PL-1	<b>UNIT</b>	INCH/MM
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PDS	INCH		MM	
	MIN	MAX	MIN	MAX
A	0.170	0.181	4.318	4.597
A1	0.000	0.012	0.000	0.305
b1	0.047	0.053	1.194	1.346
C1	0.012	0.023	0.305	0.584
D	0.330	0.361	8.382	9.169
E	0.396	0.420	10.058	10.668
e	0.095	0.105	2.413	2.667
F	0.045	0.055	1.143	1.397
H	0.575	0.625	14.605	15.875
J1	0.080	0.120	2.032	3.048
L1	0.090	0.110	2.286	2.794
K	0.045	0.066	1.143	1.676
theta 1	3°	10°	3°	10°
theta 2	1°	7°	1°	7°
theta 3	0°	8°	0°	8°
theta 4	18°	22°	18°	22°
Q	0.055	0.075	1.397	1.905
U	0.256	Ref.	6.502	Ref.
V	0.303	Ref.	7.696	Ref.

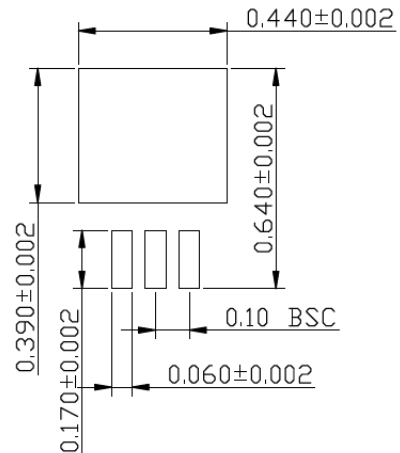
TOP VIEW

SIDE VIEW 1



BOTTOM VIEW

SIDE VIEW 2



RECOMMENDED LAND PATTERN (UNIT: INCH)

**NOTES:**

FOOT LENGTH USE GAUGE PLANE METHOD MEASUREMENT 0.010"

Note: For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>.

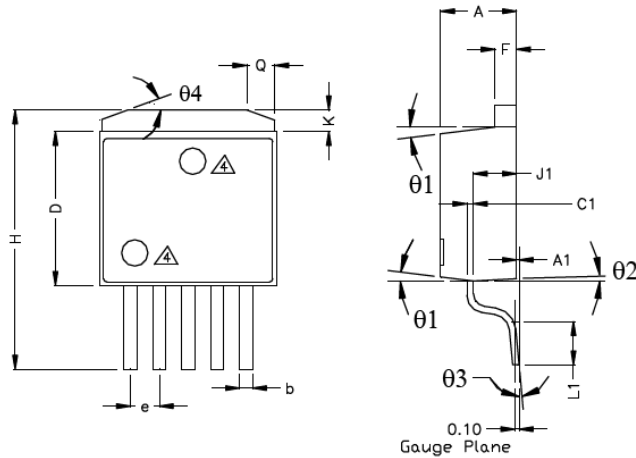
# MIC39300/01/02

## 5-Lead TO-263 Package Outline and Recommended Land Pattern

**TITLE**

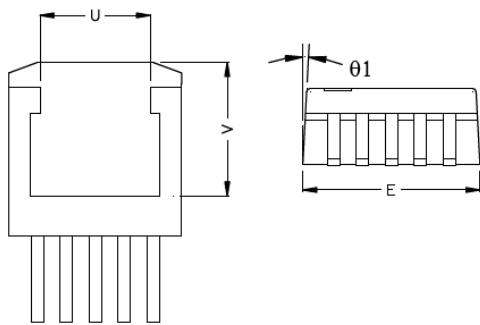
5 LEAD T0263 PACKAGE OUTLINE & RECOMMENDED LAND PATTERN

<b>DRAWING #</b>	T0263-5LD-PL-1	<b>UNIT</b>	INCH/MM
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TOP VIEW

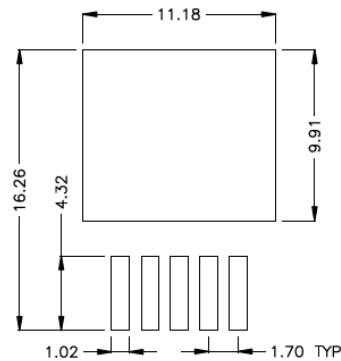
SIDE VIEW 1



BOTTOM VIEW

SIDE VIEW 2

POS	INCH		MM	
	MIN	MAX	MIN	MAX
A	0.170	0.181	4.318	4.597
A1	0.000	0.012	0.000	0.305
b	0.026	0.036	0.660	0.914
C1	0.012	0.023	0.305	0.584
D	0.330	0.361	8.392	9.169
E	0.396	0.420	10.058	10.668
e	0.062	0.072	1.575	1.829
F	0.045	0.055	1.143	1.397
H	0.575	0.625	14.605	15.875
J1	0.080	0.120	2.032	3.048
K	0.045	0.066	1.143	1.676
L1	0.090	0.110	2.286	2.794
θ1	3°	10°	3°	10°
θ2	1°	7°	1°	7°
θ3	0°	8°	0°	8°
θ4	18°	22°	18°	22°
Q	0.055	0.075	1.397	1.905
U	0.256	Ref.	6.502	Ref.
V	0.305	Ref.	7.747	Ref.



RECOMMENDED LAND PATTERN  
(UNIT : mm)

- NOTE:
1. PACKAGE OUTLINE EXCLUSIVE OF MOLD FLASH & METAL BURR.
  2. PACKAGE OUTLINE INCLUSIVE OF PLATING THICKNESS.
  3. FOOT LENGTH USING GAUGE PLANE METHOD MEASUREMENT 0.010"
  4. PACKAGE TOP MARK MAY BE IN TOP CENTER OR LOWER LEFT CORNER
  5. ALL DIMENSIONS ARE IN INCHES/MILLIMETERS.

Note: For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>.

## APPENDIX A: REVISION HISTORY

### Revision A (May 2018)

- Converted Micrel document MIC39300/01/02 to Microchip data sheet DS20006017A.
- Minor text changes throughout.

NOTES:





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